

Guideline for wire bond to MXP400x bare die. Recommend Wedge Bond used.

Wedge detail informations:

- * 45 degree wire feed angle.
- * .0015 in. hole size.
- * .001 in. bond length .
- * Flat face.
- * Cermet-tip (Recommended for gold wire)

Bonder set up with :

- * Heated work holder set at 150 Degree C.
- * Bonding force set at 18 Grams
- * First bond set at : 5 W. 7 ms .

Wire :

0.7 mil Dia gold wire.
Gold (1 to 3% elongation)

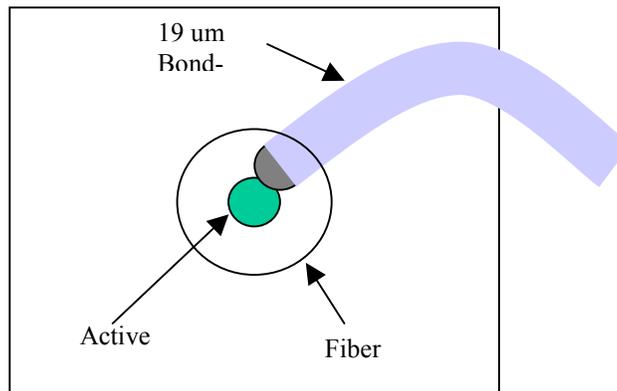
note : reference bonder:

WEST BOND
Model : 7400-15A-32-34

Metalization:

Titanium/Platinum/Gold (top surface)

Note: The inert area surrounding the active area and bond pad has passivation and is therefore insulated. The bottom is the cathode and is conducting



PRECAUTIONS FOR USE

ESD protection is important. Standard ESD protection procedures should be employed whenever handling InGaAs PIN photo diode.

IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>